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down position, in accordance with one embodiment of the present invention. As shown, the chuck assembly includes a chuck top plate 2110 defined on top of the chuck body 102. The chuck assembly 1400 includes a plurality of linkage arms 122, grippers 112, linkage pins 122a, and rotation pins 120, with each of the grippers being coupled to the respective linkage arm via the respective linkage pin 122a, while each of the grippers 112 is coupled to the chuck body 102 via the respective rotation pin 120. As shown, grippers 112 are configured to generally function as substrate holders.

Page 38, paragraph 2, lines 19-24 to page 39, paragraph 1, line 1:

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However, as the RPMs of the chuck assembly decreases, the backside pin 2129 of the wafer backside plate 2114 traverses back through the height adjusting slot 2128a from the height B to the height A so as to assume the down position. Having a wafer backside plate 2114 configured to be moved from the up position to a down position is beneficial as the gap between the wafer backside plate 2114 and the wafer 118 allows the end effector to approach the wafer process plane so as to load/unload a processed wafer.

The amendments to the specification are shown using bracketing and underlining in the attached "Marked-Up Specification and Claims" document. It is submitted that the amendments were made to correct typographical errors, and as such, do not introduce any new matter.

IN THE CLAIMS

Please amend the claims as follows. All pending claims after this Amendment are in clean form and are listed below for the convenience of the Examiner. Attached hereto as a separate document is the "Marked-Up Specification and Claims," showing amendments using bracketing and underlining.

Please cancel claims 6, 7, 13, 14 and 20-30.

- SubD2
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1. (Amended) An apparatus for preparing a wafer, comprising:
a wafer backside plate having a top surface configured to include a cylindrical edge lip that defines a central aperture;